

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Jimarez et al.

Art Unit:

Serial No.:

Dkt. No.: END919980110US4

Filed:

Examiner:

Title: **FLIP CHIP C4 EXTENSION STRUCTURE AND PROCESS**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Preliminary Amendment

Sir:

Kindly enter this amendment prior to initial examination

In the Specification:

Page 1, between lines 1 and 2, insert: --This application is a divisional of Serial No. 09/782,471; filed on 2/12/2001.--

The paragraph beginning on page 35, line 7 is amended as follows:

FIGS. 23-28 illustrate process steps associated with a fourth embodiment of the present invention. FIG. 23 shows the first structure 10 of FIG. 1 such that the coat of material 18 of FIG. 1 is replaced by the volume of material 19 of FIG. 23. The volume of material 19 of FIG. 23 may include any material (e.g., a nonsolderable and nonconductive material such as a polyimide or a photosensitive resin) that could be included in the coat of material 18 of FIG. 1, or additionally epoxy adhesive or silicone adhesive. The first substrate 12 (e.g., chip, module), first conductive bodies 14 (e.g., solder bump such as C4 solder ball), and pads 16 in FIG. 23 are the same as in